

BYK-1765

Solvent- and silicone-free defoamer for high-solid and solvent-free systems with particular suitability for epoxy systems.

Product data

Composition

Polyacrylate

Solvent-free

Typical properties

The values indicated in this data sheet describe typical properties and do not constitute specification limits.

Density (20 °C): 0.99 g/ml
 Active substance: 100 %
 Flash point: 100 °C
 Appearance: colorless, clear

Applications

Coatings industry

Special features and benefits

BYK-1765 is an excellent solvent- and silicone-free acrylic defoamer for high-solid and solvent-free systems and is especially recommended for epoxy systems. The additive is highly effective against macro- and microfoam while maintaining good system compatibility. Particularly in thick film applications, where foam bubble rise and defoaming are a major challenge, BYK-1765 is very efficient. The use of the additive shows no negative influence on recoatability and intercoat adhesion. In addition, leveling is influenced positively. The highly efficient defoaming can also improve the functionality, such as the anti-corrosion properties in protective systems.

Recommended use

Marine coatings	<input checked="" type="checkbox"/>
Protective coatings	<input checked="" type="checkbox"/>
Floor coatings	<input checked="" type="checkbox"/>
General industrial coatings	<input type="checkbox"/>

especially recommended recommended

Recommended levels

0.3–2.0 % additive (as supplied) based on the total formulation.

The above recommended levels can be used for orientation. The optimum dosage should be determined by application-related test series.

Incorporation and processing instructions

BYK-1765 is easy to incorporate and can be added at any stage of the production process. However, incorporation in the letdown or as post-addition with medium shear forces is recommended.

Adhesives and sealants

Special features and benefits

BYK-1765 is a very effective solvent- and silicone-free acrylic defoamer for high-solid and solvent-free systems and is particularly recommended for adhesives based on epoxy resins. The additive is very efficient against macro- and micro-foam while maintaining good system compatibility. Especially in high layer thickness applications, where foam bubble rise and defoaming are a major challenge, BYK-1765 is very effective. The use of the additive shows no negative influence on intercoat adhesion. In addition, leveling is influenced positively.

Recommended levels

0.3–2.0 % additive (as supplied) based on the total formulation.

The above recommended levels can be used for orientation. The optimum dosage should be determined by application-related test series.

Incorporation and processing instructions

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This issue replaces all previous versions.